

Patent Application No. 10/690,113

IN THE CLAIMS:

Please amend claims 1-3 and 17, and add claims 27-31 as follows:

Claim 1. (currently amended) A trace cover suitable for shielding a conductive trace on a circuit board, the circuit board includes at least one circuit ground, the trace cover comprising:

5 a body composed of a dielectric substrate, the body having a top surface, a bottom surface and side surfaces, the bottom surface of the body configured to be disposed substantially over the conductive trace; and

10 top shielding disposed on the top surface of the body, the top shielding configured to be ~~being~~ electrically coupled with the at least one circuit ground of the circuit board.

Claim 2. (currently amended) The trace cover of claim 1, further comprising side shielding perpendicular to the direction of the ~~signal~~ conductive trace and substantially parallel to the length of the conductive trace, the side shielding configured to be ~~being~~ electrically coupled with the at least one circuit ground of the circuit board.

Claim 3. (currently amended) The trace cover of claim 2, further comprising at least one connecting pad disposed on the bottom surface of the body, the connecting pad configured to be soldered to a top surface of the circuit board and to electrically couple the side shielding with the at least one circuit ground.

Claim 4. (original) The trace cover of claim 2, wherein the side shielding includes a plurality of conductive vias disposed between the top surface and bottom surface of the body.

Claim 5. (original) The trace cover of claim 4, wherein the plurality of conductive vias are spaced approximately one-quarter inch apart.

Claim 6. (original) The trace cover of claim 2, wherein the side shielding includes a conductive plating disposed along the side surfaces of the body.

Claim 7. (original) The trace cover of claim 1, wherein the top shielding is a conductive plating.

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Claim 8. (original) The trace cover of claim 1, wherein the top shielding is electrically coupled to the circuit ground through the side shielding.

Claim 9. (original) The trace cover of claim 1, wherein the dielectric substrate of the body is different than a dielectric substrate of the circuit board.

Claims 10-16 (canceled)

Claim 17. (currently amended) A circuit board comprising:
a conductive trace disposed on an outer ~~layer~~ surface of the circuit board; and
means for shielding the conductive trace.

Claim 18. (original) A trace cover suitable for suppressing electromagnetic emissions from a conductive bus on a circuit board, the conductive bus including at least two substantially parallel bus traces, the circuit board including at least one circuit ground, the
5 trace cover comprising:

a body composed of a dielectric substrate, the body having a top surface, a bottom surface and side surfaces, the bottom surface of the body configured to be disposed substantially over the conductive bus;
side shielding perpendicular to the direction of the conductive
10 bus and substantially parallel to the length of the conductive bus, the side shielding being electrically coupled with the at least one circuit ground of the circuit board; and
top shielding disposed on the top surface of the body, the top shielding being electrically coupled with the at least one circuit
15 ground of the circuit board.

Claim 19. (original) The trace cover of claim 18, further comprising bus shielding disposed within the body and between the bus traces, the bus shielding being electrically coupled with the at least one circuit ground of the circuit board.

Claim 20. (original) The trace cover of claim 19, further comprising at least one connecting pad disposed on the bottom surface of the body, the connecting pad configured to coupled the bus shielding with the at least one circuit ground.

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Claim 21. (original) The trace cover of claim 19, wherein the bus shielding includes a plurality of conductive vias disposed between the top surface and bottom surface of the body.

Claim 22. (original) The trace cover of claim 19, wherein the bus shielding is coupled to the circuit ground through the side shielding.

Claim 23. (original) The trace cover of claim 18, wherein the side shielding includes a conductive plating disposed along side surfaces of the body.

Claims 24-26. (canceled)

Claim 27. (new) The trace cover of claim 1, wherein the trace cover is mechanically attached to a top surface of the circuit board after manufacture of the circuit board.

Claim 28. (new) The trace cover of claim 1, wherein the conductive trace is on an outer surface of the circuit board.

Claim 29. (new) The trace cover of claim 1, wherein the trace cover is separate from the circuit board and is configured to be attachable to the circuit board during circuit board component attachment.

Claim 30. (new) The trace cover of claim 18, wherein the conductive bus is on an outer surface of the circuit board.

Claim 31. (new) The trace cover of claim 18, wherein the trace cover is separate from the circuit board and is configured to be attachable to the circuit board during circuit board component attachment.